

Amendments to the Abstract:

Please replace the paragraph beginning at page 6, line 2, with the following rewritten paragraph:

- An integrated circuit package ~~having central leads~~ comprises a substrate
5 ~~has~~having an upper surface, a lower surface, and a long slot penetrating ~~from~~the upper surface to the lower surface. The lower surface is ~~forming~~formed with a wiring regions arranged at the ~~two sides~~one side of the long slot, and the wiring regions ~~are~~is ~~forming~~formed with a plurality of ~~connected~~connection points. A glue layer is coated on the upper surface of the substrate and is arranged at the
10 periphery of the long slot. The integrated circuit has a first surface ~~forming~~formed with a plurality of bonding pads ~~and~~, which is adhered to the glue layer. The wires, each of which is arranged within the long slot of the substrate, and is electrically connected the bonding pads of the integrated circuit to the ~~connected~~connection points of the substrate.; and The first compound layer is filled within
15 the long slot of the substrate ~~for protecting to protect~~ the each-wires. --